

MC74AC10, MC74ACT10

Triple 3-Input NAND Gate

Features

- Outputs Source/Sink 24 mA
- 'ACT10 Has TTL Compatible Inputs
- Pb-Free Packages are Available

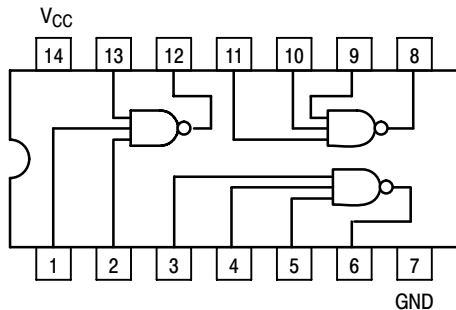


Figure 1. Pinout: 14-Lead Packages Conductors
(Top View)

MAXIMUM RATINGS

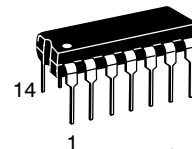
Rating	Symbol	Value	Unit
DC Supply Voltage (Referenced to GND)	V_{CC}	-0.5 to +7.0	V
DC Input Voltage (Referenced to GND)	V_{in}	-0.5 to $V_{CC} + 0.5$	V
DC Output Voltage (Referenced to GND)	V_{out}	-0.5 to $V_{CC} + 0.5$	V
DC Input Current, per Pin	I_{in}	± 20	mA
DC Output Sink/Source Current, per Pin	I_{out}	± 50	mA
DC V_{CC} or GND Current per Output Pin	I_{CC}	± 50	mA
Storage Temperature	T_{stg}	-65 to +150	$^{\circ}C$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

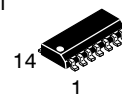


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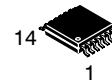
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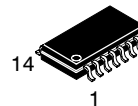
PDIP-14
N SUFFIX
CASE 646



SOIC-14
D SUFFIX
CASE 751A



TSSOP-14
DT SUFFIX
CASE 948G



SOEIAJ-14
M SUFFIX
CASE 965

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

MC74AC10, MC74ACT10

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit	
V _{CC}	Supply Voltage	'AC	2.0	5.0	6.0	V
		'ACT	4.5	5.0	5.5	
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Ref. to GND)	0	–	V _{CC}	V	
t _r , t _f	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V _{CC} @ 3.0 V	–	150	–	ns/V
		V _{CC} @ 4.5 V	–	40	–	
		V _{CC} @ 5.5 V	–	25	–	
t _r , t _f	Input Rise and Fall Time (Note 2) 'ACT Devices except Schmitt Inputs	V _{CC} @ 4.5 V	–	10	–	ns/V
		V _{CC} @ 5.5 V	–	8.0	–	
T _J	Junction Temperature (PDIP)	–	–	140	°C	
T _A	Operating Ambient Temperature Range	–40	25	85	°C	
I _{OH}	Output Current – High	–	–	–24	mA	
I _{OL}	Output Current – Low	–	–	24	mA	

1. V_{in} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{in} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74AC		74AC	Unit	Conditions
			T _A = +25°C		T _A = –40°C to +85°C		
			Typ	Guaranteed Limits			
V _{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V _{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V _{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I _{OUT} = –50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	–	2.56	2.46	V	*V _{IN} = V _{IL} or V _{IH} –12 mA I _{OH} –24 mA –24 mA
		4.5	–	3.86	3.76		
5.5	–	4.86	4.76				
V _{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I _{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	–	0.36	0.44	V	*V _{IN} = V _{IL} or V _{IH} 12 mA I _{OL} 24 mA 24 mA
		4.5	–	0.36	0.44		
5.5	–	0.36	0.44				
I _{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0	μA	V _I = V _{CC} , GND
I _{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}		5.5	–	–	–75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40	μA	V _{IN} = V _{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

MC74AC10, MC74ACT10

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V _{CC} * (V)	74AC			74AC		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = –40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
t _{PLH}	Propagation Delay	3.3 5.0	1.5 1.5	6.0 4.5	9.5 7.0	1.0 1.0	10.5 8.0	ns	3–5
t _{PHL}	Propagation Delay	3.3 5.0	1.5 1.5	5.5 4.0	8.5 6.0	1.0 1.0	10.0 6.5	ns	3–5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.
Voltage Range 5.0 V is 5.0 V ±0.5 V.

DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74ACT		74ACT		Unit	Conditions
			T _A = +25°C		T _A = –40°C to +85°C			
			Typ	Guaranteed Limits				
V _{IH}	Minimum High Level Input Voltage	4.5	1.5	2.0	2.0		V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
		5.5	1.5	2.0	2.0			
V _{IL}	Maximum Low Level Input Voltage	4.5	1.5	0.8	0.8		V	V _{OUT} = 0.1 V or V _{CC} – 0.1 V
		5.5	1.5	0.8	0.8			
V _{OH}	Minimum High Level Output Voltage	4.5	4.49	4.4	4.4		V	I _{OUT} = –50 μA
		5.5	5.49	5.4	5.4			
		4.5	–	3.86	3.76		V	*V _{IN} = V _{IL} or V _{IH} –24 mA I _{OH} –24 mA
		5.5	–	4.86	4.76			
V _{OL}	Maximum Low Level Output Voltage	4.5	0.001	0.1	0.1		V	I _{OUT} = 50 μA
		5.5	0.001	0.1	0.1			
		4.5	–	0.36	0.44		V	*V _{IN} = V _{IL} or V _{IH} 24 mA I _{OL} 24 mA
		5.5	–	0.36	0.44			
I _{IN}	Maximum Input Leakage Current	5.5	–	±0.1	±1.0		μA	V _I = V _{CC} , GND
ΔI _{CC} T	Additional Max. I _{CC} /Input	5.5	0.6	–	1.5		mA	V _I = V _{CC} – 2.1 V
I _{OLD}	†Minimum Dynamic Output Current	5.5	–	–	75		mA	V _{OLD} = 1.65 V Max
I _{OHD}		5.5	–	–	–75		mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	–	4.0	40		μA	V _{IN} = V _{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

MC74AC10, MC74ACT10

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V _{CC} * (V)	74ACT			74ACT		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = –40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
t _{PLH}	Propagation Delay	5.0	1.0	–	9.0	1.0	10.0	ns	3–5
t _{PHL}	Propagation Delay	5.0	1.0	–	9.0	1.0	9.5	ns	3–5

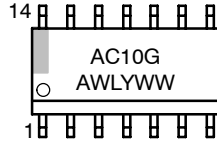
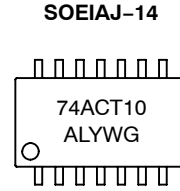
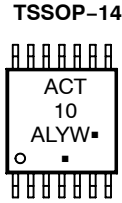
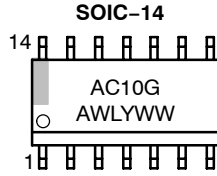
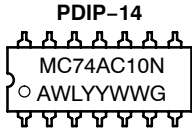
*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	25	pF	V _{CC} = 5.0 V

MC74AC10, MC74ACT10

MARKING DIAGRAMS



A = Assembly Location
 WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G or ■ = Pb-Free Package
 (Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74AC10N	PDIP-14	25 Units/Rail
MC74AC10NG	PDIP-14 (Pb-Free Package)	
MC74ACT10N	PDIP-14	
MC74ACT10NG	PDIP-14 (Pb-Free Package)	55 Units/Rail
MC74AC10D	SOIC-14	
MC74AC10DG	SOIC-14 (Pb-Free Package)	2500/Tape & Reel
MC74AC10DR2	SOIC-14	
MC74AC10DR2G	SOIC-14 (Pb-Free Package)	55 Units/Rail
MC74ACT10D	SOIC-14	
MC74ACT10DR2	SOIC-14	
MC74ACT10DR2G	SOIC-14 (Pb-Free Package)	2500/Tape & Reel
MC74ACT10DTR2	TSSOP-14*	
MC74ACT10DTR2G	TSSOP-14*	50 Units/Rail
MC74AC10M	SOEIAJ-14	
MC74ACT10MEL	SOEIAJ-14	
MC74ACT10MELG	SOEIAJ-14 (Pb-Free Package)	2000/Tape & Reel

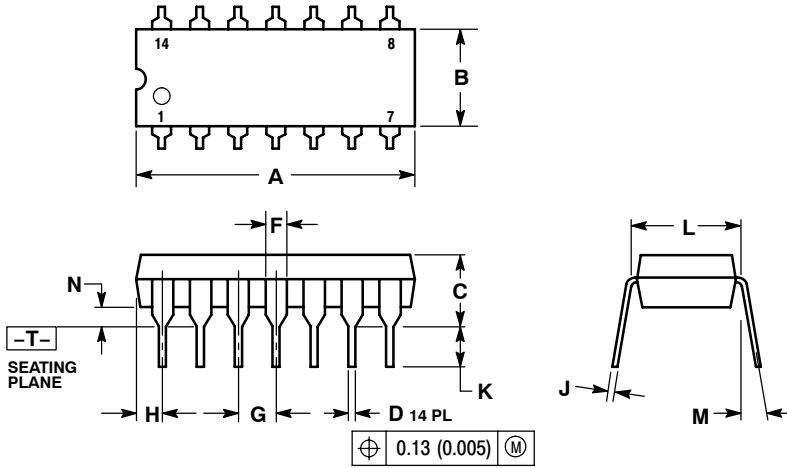
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

MC74AC10, MC74ACT10

PACKAGE DIMENSIONS

PDIP-14
CASE 646-06
ISSUE P



NOTES:

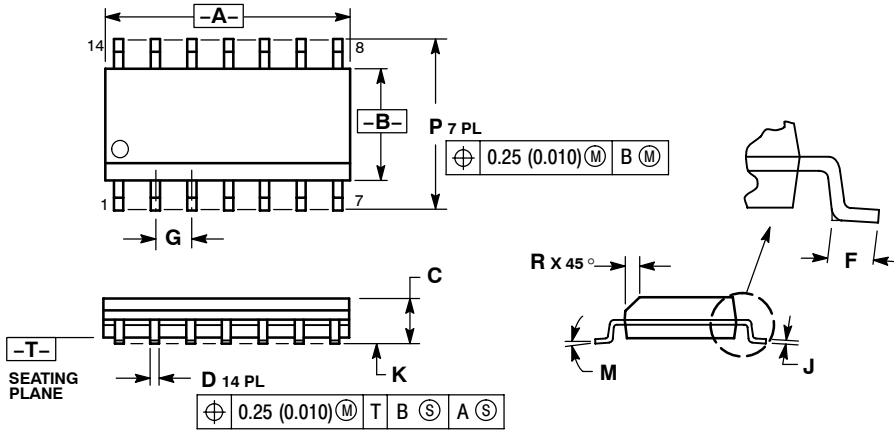
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.715	0.770	18.16	19.56
B	0.240	0.260	6.10	6.60
C	0.145	0.185	3.69	4.69
D	0.015	0.021	0.38	0.53
F	0.040	0.070	1.02	1.78
G	0.100 BSC		2.54 BSC	
H	0.052	0.095	1.32	2.41
J	0.008	0.015	0.20	0.38
K	0.115	0.135	2.92	3.43
L	0.290	0.310	7.37	7.87
M	---	10°	---	10°
N	0.015	0.039	0.38	1.01

MC74AC10, MC74ACT10

PACKAGE DIMENSIONS

SOIC-14
CASE 751A-03
ISSUE H

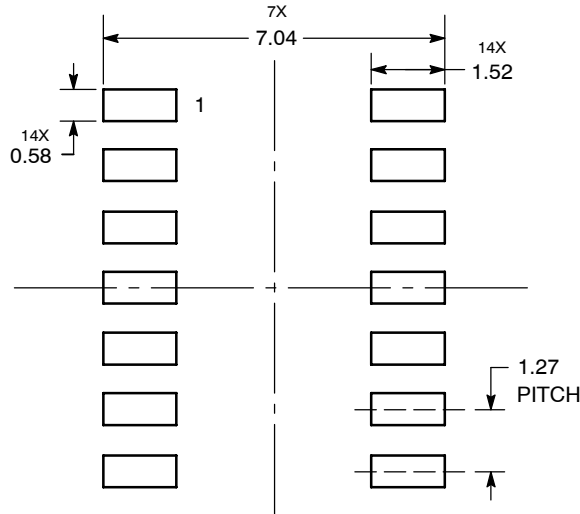


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*



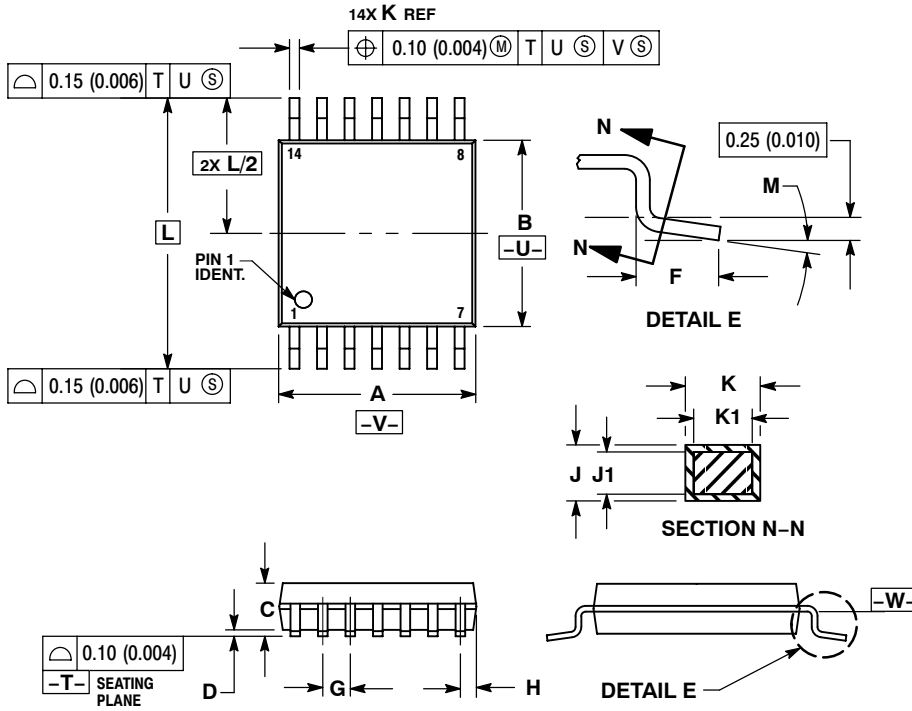
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC74AC10, MC74ACT10

PACKAGE DIMENSIONS

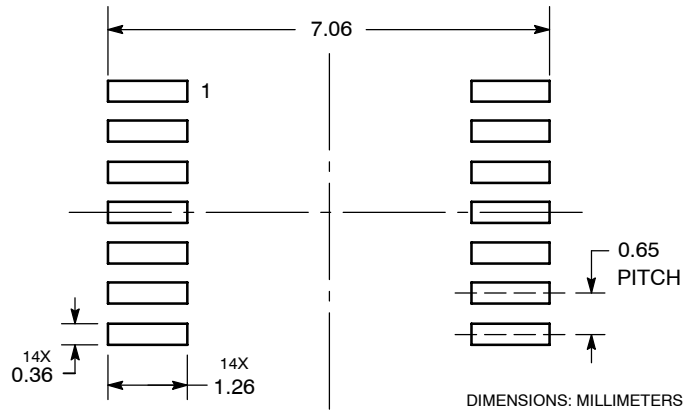
TSSOP-14
CASE 948G-01
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0° 8°		0° 8°	

SOLDERING FOOTPRINT*

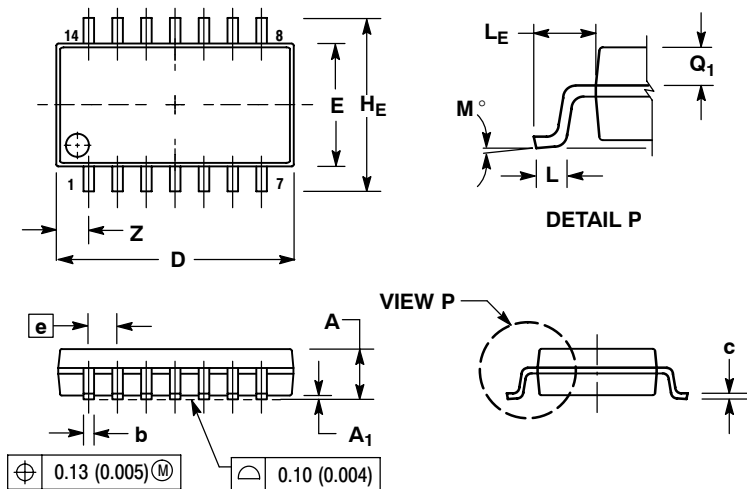


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MC74AC10, MC74ACT10

PACKAGE DIMENSIONS

SOEIAJ-14
CASE 965-01
ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.004	0.008
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
0.50	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0°	10°	0°	10°
Q ₁	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

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